

Intel[®] Server Board S875WP1-E Memory List Test Report Summary



*Revision 43.0
August 2006*

Revision History		
Date	Rev	Modifications
May/03	1.0	Initial release.
June/03	2.0	Added MSC & Micron 128MB parts. Buffalo, MSC, Infineon and Viking 256MB parts. (in shaded area)
June/03	3.0	Added Dataram 256MB, 512MB and 1GB parts. Added Viking and ATP 512MB parts. Added Infineon 512MB & 1G parts. Added Samsung 256MB & 512MB parts. (In shaded area). Also updated EOL status
July/03	4.0	Added ATP 256MB and 512MB parts. Added Legend 512MB parts. Added Viking 1GB parts. (In shaded area) Also updated EOL status.
July/03	5.0	Added Buffalo and ATP 256MB parts. Added Legend, Buffalo, ATP and Centon 512MB parts. Added Infineon 128MB & 512MB parts. Added Micron 128MB part. (In shaded area)
Aug/03	6.0	Added Centon 256MB & 512MB parts. Added Micron 128MB & 256MB parts. Added Samsung 256MB & 512MB parts. Added Buffalo, Dataram, Smart, & Ventura 512MB parts. Added Viking 1GB parts.
Sept/03	7.0	Added Dataram & Samsung 256MB parts. Added TRS 1GB parts. (In shaded area)
Sept/03	8.0	Added TRS and Ventura 512MB parts. Added Micron 128MB part. Added Samsung 128MB & 256MB parts. Added Infineon 256MB parts. (In shaded area)
Oct/03	9.0	Added TRS 256MB parts. Added ATP 512MB parts. (In shaded area)
Nov/03	10.0	Added Viking and Buffalo 256MB parts. Added Samsung 128MB & 512MB parts. Added Micron 256MB & 512MB parts. (In shaded area)
Nov/03	11.0	Added Legend 128MB part. Added Viking 512MB parts. Added Smart 1GB part. (In shaded area)
Nov/03	12.0	Added Viking, Dataram, Ventura, and Centon 512MB parts. (In shaded area)
Dec/03	13.0	Added Centon 512MB and 1GB parts. (In shaded area)
Jan/04	14.0	Added TRS and Centon 256MB parts. Added ATP, Centon and Ventura 512MB parts. (In shaded area)
Feb/04	15.0	Added Legend 256MB parts. Added ATP 512MB parts. Added Smart and Legend 1GB parts. (In shaded area). Added Micron 256MB & 1G parts. Added Infineon 256MB & 512MB parts. Also updated EOL status.
Feb/04	16.0	Added Simple, TRS and Dane-elec 512MB parts. Added Buffalo 1GB parts. Added Infineon 1G part. New address for CMTL (In shaded area)
Mar/04	17.0	Added Dane-elec 256MB and 512MB parts. Added ATP 1GB parts. (In shaded area)
Mar/04	18.0	Added Dane-elec and Legend 512MB parts. Added Avant 1GB parts. (In shaded area). And updated EOL status
Apr/04	19.0	Added Smart and Legend 512MB parts. Added ATP and Legend 1GB parts. (In shaded area)
May/04	20.0	Added Legend and Viking 256MB parts. Added ATP, Legacy, Micron, Viking, and Smart 512MB parts. Added ATP 1GB parts. Added Micron 256MB & 512MB parts. Added Infineon 512MB & 1G parts. (In shaded area)
Jun/04	21.0	Added Buffalo Dane-elec & Ventura 256MB parts. Added Dane-elec & Viking 512MB parts. Added Dataram, TRS, Ventura & Buffalo 1GB parts. (In shaded area)
Jun/04	22.0	Added Dane-Elec, Ventura, & Legend 256Mb parts. Added Legend & Micron 512MB parts. Added Legend & Ventura 1GB parts. Added Infineon 256MB & 512MB parts. (In shaded area)
Jul/04	23.0	Added Buffalo and Smart 256MB, 512MB and 1GB parts. (In shaded area)
Aug/04	24.0	Added Wintec 512MB parts. Added 1GB Kingston parts. (In shaded area)
Aug/04	25.0	Added Buffalo and Legend 512MB parts. Added Apacer and TRS 1GB parts. (In shaded area)
Oct/04	26.0	Added Apacer and Legend 256MB parts. Added Apacer, Buffalo, and Legend 512MB parts. (In shaded area)
Oct/04	27.0	Added Buffalo 512MB and 1GB parts. (In shaded area)
Dec/04	28.0	Added Buffalo, TRS, and Smart 512MB parts. (In shaded area)
Dec/04	29.0	Added Buffalo 1GB parts. (In shaded area)
Jan/05	30.0	Added Kingston 512MB parts. (In shaded area)
Feb/05	31.0	Added Infineon 256MB part. Added Buffalo and Dataram 512MB parts. (In shaded area)
Feb/05	32.0	Added Buffalo 2565MB part. (In shaded area)
Mar/05	33.0	Added Dataram 256MB and Buffalo 512MB parts. (In shaded area)
Apr/05	34.0	Added Viking 512MB and 1GB parts. Added Samsung and Micron 1GB parts. (In shaded area)
Apr/05	35.0	Added Buffalo 256MB parts. Added Viking 512MB parts. Added Legacy 1GB parts. (In shaded area)
May/05	36.0	Updated contact info.
Aug/05	37.0	Added TRS 1GB parts. (In shaded area)

Revision History		
Date	Rev	Modifications
Aug/05	38.0	Added Avant 1GB part. (In shaded area)
Nov/05	39.0	Added Avant 1GB part. (In shaded area)
Dec/05	40.0	Added Legend 256MB part. (In shaded area)
Jan/06	41.0	Added Legend 512MB part. (In shaded area)
July/06	42.0	Added Buffalo and Smart 1GB parts. (In shaded area)
Aug/06	43.0	Added Smart 1GB part. (In shaded area)

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The Intel® Server Board S875WP1-E may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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Please Note: DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended.

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Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board S875WP1-E. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)¹. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel's Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft* Windows* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

¹ CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Main Office: (949) 716-8690
Main Fax (949) 716-8691

Computer Memory Test Lab (CMTL)
24 Hammond Suite F
Irvine, CA 92618
<http://www.cmtlabs.com/>

Qualified Memory for the Intel® Server Board S875WP1-E

The memory module on the server board S875WP1-E has 4 DIMM sockets, which can hold up to 4 GB of Unbuffered ECC and non-ECC DDR266, DDR333 or DDR400 memory using four 72-bit DIMM modules. The following memory features are supported:

- DDR266, DDR333 and DDR400 Unbuffered ECC and non-ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification)
- DIMMs with capacity of 128MB, 256 MB, 512 MB, 1G. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 128MB using one 128MB DIMM.

Please Note: The S875WP1-E Tested Memory List is valid for all S875WP1-E Product Codes (S875WP1 and S875WP1LX).

Below is a chart that lists the current supported memory types:

DDR266, DDR333 and DDR400 Unbuffered DRAM Module Configurations for Cas Latency 2 & 2.5					
DIMM Capacity	DIMM Organization	DRAM Density	DRAM Organization	# DRAM Devices/rows/Banks	# Address bits rows/Banks/column
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11

Memory features are detailed in the *Intel® Server Board S875WP1-E Technical Product Specification* available on-line at <http://support.intel.com/support/motherboards/server/S875WP1-E>

The following table lists DIMM devices known to be compatible with the Intel Server Board S875WP1-E. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

Caution: Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

Note: This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

This list is subject to change without notice.

Server Board S875WP1-E

Unbuffered, ECC, DDR266 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+MSC Vertriebs GmbH	MSC128M00073	K4H280838C-TCB0 rev C	Samsung	M0498LA1	5/21/03	2.5	Yes	(16Mx8)*9	EOL
Infineon	HYS72D16000GU-7-A	HYB250D128800AT-7A	Infineon		7/15/03	2	Yes	(16Mx8)*9	
Micron	MT9VDDT1672AG-265B1	MT46V16M8-75 B	Micron		7/15/03	2.5	Yes	(16Mx8)*9	
Samsung	M381L1713DTL-CA2	K4H280838D-TCA2	Samsung		9/8/03	2	Yes	(16Mx8)*9	

Unbuffered, ECC, DDR333 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT1672AG-335B4	MT46V16M8-6TB	Micron		5/27/03	2.5	Yes	(16Mx8)*9	
Samsung	M381L1713ETM-CB3	K4H280838E-TCB3	Samsung		9/25/03	2.5	Yes	(16Mx8)*9	

Unbuffered, ECC, DDR400 DIMM Modules 128MB Sizes (16Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT1672AG-40BB5	MT46V16M8-5B	Micron		8/20/03	3	Yes	(16Mx8)*9	
Samsung	M381L1713ETM-CCC	K4H280838E-TCCC	Samsung		9/19/03	3	Yes	(16Mx8)*9	
Micron	MT5VDDT1672AG-40BC3	MT46V16M16-5B C	Micron		9/23/03	3	Yes		

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Server Board S875WP1-E

Unbuffered, Non-ECC, DDR266 DIMM Modules 128MB Sizes (16Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR333 DIMM Modules 128MB Sizes (16Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR400 DIMM Modules 128MB Sizes (16Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Server Board S875WP1-E

Unbuffered, ECC, DDR266 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD266-E256/MB	MT46V16M8-75 rev B	Micron	UE0502-AA rev A	5/16/03	2.5	Yes	(16Mx8)*18	
+MSC Vertriebs GmbH	MSC256M00075	K4H560838C-TCB0 rev C	Samsung	M0498LA1	5/19/03	2.5	Yes	(16Mx8)*18	EOL
+MSC Vertriebs GmbH	MSC256M00079	HYB25D256800AT-7 rev A	Infineon	M0498LA1	5/19/03	2.5	Yes	(32Mx8)*9	EOL
Samsung	M381L3223DTL-CA2	K4H560838D-TCA2	Samsung		6/13/03	2	Yes	(32Mx8)*9	
+Centon Electronics	TOP02-D014N	MT46V32M8TG-75 rev C	Micron	86ESD04A rev A	7/24/03	2.5	Yes	(32Mx8)*9	
Infineon	HYS72D32000GU-7-A	HYB25D256800AT-7A	Infineon		9/8/03	2	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CA2	K4H560838E-TCA2	Samsung		9/18/03	2	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CB0	K4H560838E-TCB0	Samsung		9/18/03	2.5	Yes	(32Mx8)*9	
+TRS* Tele-Radio-Space GmbH	TRS20156	HYB25D256800BT-7 rev B	Infineon	M0498LA1 rev 1	9/19/03	2	Yes	(32Mx8)*9	
Micron	MT9VDDT3272AG-265C4	MT46V32M8-75 C	Micron		10/10/03	2.5	Yes	(32Mx8)*9	
Micron	MT9VDDT3272AG-265B1	MT46V32M8-75 B	Micron		10/10/03	2.5	Yes	(32Mx8)*9	
Infineon	HYS72D32300HU-6-C	HYB25D256800CE-6C	Infineon		2/9/04	2.5	Yes	(32Mx8)*9	

Unbuffered, ECC, DDR333 DIMM Modules 256MB Sizes (32Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+ATP Electronics	AG32L72T8SQB3S	K4H560838D-TCB3 rev D	Samsung	SG184T08L1 rev 1	5/6/03	2.5	Yes	(32Mx8)*9	EOL
Micron	MT18VDDT3272A G-335B4	MT46V16M8-6TB	Micron		5/15/03	2.5	Yes	(16Mx8)*18	
Micron	MT9VDDT3272AG-335C4	MT46V32M8-6TC	Micron		5/15/03	2.5	Yes	(32Mx8)*9	
Infineon	HYS72D32300GU-6-B	HYB25D256800BT-6B	Infineon		5/27/03	2.5	Yes	(32Mx8)*9	
+Buffalo	DD333-ES256/MC	MT46V32M8TG-6T rev C	Micron	UE0832-AA	6/30/03	2.5	Yes	(32Mx8)*9	
+Buffalo	DD333-ES256/SD	K4H560838D-TCB3 rev D	Samsung	UE0832-AA	7/11/03	2.5	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CB3	K4H560838E-TCB3	Samsung		8/28/03	2.5	Yes	(32Mx8)*9	
+Centon Electronics	TOP02-D020T	MT46V32M8TG-6T rev C	Micron	86ESD04A rev A	12/16/03	2.5	Yes	(32Mx8)*9	
+Buffalo	DD333-ES256/SF	K4H560838F-TCB3 rev F	Samsung	UE0832-AA	6/15/04	2.5	Yes	(32Mx8)*9	

**Unbuffered, ECC, DDR400 DIMM Modules
256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT18VDDT3272AG-40BB5	MT46V16M8-5B	Micron		5/15/03	3	Yes	(16Mx8)*18	
+Viking	VI4CU327228DTN L1	K4H560838D-TCC4	Samsung	0000927A	5/16/03	3	Yes	(32Mx8)*9	EOL
+Dataram	DTM63671A	K4H560838D-TCC4 rev D	Samsung	40570 rev A	5/29/03	3	Yes	(32Mx8)*9	
+ATP Electronics	AG32L72T8SQC4 S	K4H560838D-TCCC rev D	Samsung	SG184T08L1	6/16/03	3	Yes	(32Mx8)*9	EOL
Micron	MT9VDDT3272AG-40BC4	MT46V32M8-558 C	Micron		8/20/03	3	Yes	(32Mx8)*9	
Samsung	M381L3223ETM-CCC	K4H560838E-TCCC	Samsung		8/20/03	3	Yes	(32Mx8)*9	
+Dataram	DTM63671B	HYB25D256800BT-5 rev B	Infineon	40570 rev A	8/14/03	3	Yes	(32Mx8)*9	
Infineon	HYS72D32300GU-5-B	HYB25D256800BT-5B	Infineon		9/2/03	3	Yes	(32Mx8)*9	
+TRS	TRS20172	HYB25D256800BT-5 rev B	Infineon	M0534LA1 rev 1	12/24/03	3	Yes	(32Mx8)*9	
+Legend	L3272DC7-DR1HDC9B	HY5DU56822BT-D43 rev B	Hyundai	DR720818C1 rev 1	1/07/04	3	Yes	(32Mx8)*9	
Micron	MT9VDDT3272AG-40BG4	MT46V32M8-5B G	Micron		3/15/04	3	Yes	(32Mx8)*9	
+Viking	VI4CU327228DTP L2	V58C2256804SAT 5B rev B	Mosel Vitelic	0000981A	4/29/04	3	Yes	(32Mx8)*9	
Infineon	HYS72D32300HU-5-C	HYB25D256800CE-5C	Infineon		4/23/04	3	Yes	(32Mx8)*9	
+Legend	L3272DC7-MA6HDC9C	HY5DU56822CT-D43 rev C	Hyundai	BDMA83A6 rev 6	6/9/04	3	Yes	(32Mx8)*9	
+Smart Modular Technologies	SM3272DDR2N1-IC	HYB25D256800CE-5 rev C	Infineon	184-30-3	6/11/04	3	Yes	(32Mx8)*9	
+Buffalo	DD4333-ES256/SF	K4H560838F-TCCC rev F	Samsung	UE0832-AA	6/23/04	3	Yes	(32Mx8)*9	
+Buffalo	DD4333-ES256/IB	HYB25D256800BT-5 rev B	Infineon	UE0832-AA	6/24/04	3	Yes	(32Mx8)*9	
+Apacer	77.10638.335	HYB25D256800CE-5 rev C	Infineon	48.16118.015 rev 5	9/17/2004	3	Yes	(32Mx8)*9	
+Legend	L3272DC7-MA6HDC9D	HY5DU56822DT-D43 rev D	Hyundai	BDMA83A6 rev 6	9/15/2004	3	Yes	(32Mx8)*9	
Infineon	HYS72D64320GU-5-C	HYB25D256800CE	Infineon		2/1/05	3	Yes	(32Mx8)*9	
+Dataram	DTM63671C	HYB25D256800CE-5 rev C	Infineon	40570 rev A	2/17/05	3	Yes	(32Mx8)*9	
+Buffalo	DD4333-ES256/MG	MT46V32M8TG-5B rev G	Micron	UE0832-AA	4/1/05	3	Yes	(32Mx8)*9	

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Modules in bold text do not contain Lead.

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Server Board S875WP1-E

Unbuffered, Non-ECC, DDR266 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR333 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Centon Electronics	TOP02-D002B	MT46V32M8TG-6T rev C	Micron	86SD03	7/21/03	2.5	Yes	(32Mx8)*8	EOL
+Dane-Elec	OD1D333-064325I-1MC	MT46V32M8TG-5B rev C	Micron	DR5128-33	2/18/04	2.5	Yes	(32Mx8)*8	
+Legend	L3264DC6-643HDC5B	HY5DU56822BT-D43 rev B	Hyundai	DR640816A3 rev 3	10/31/03	2.5	Yes	(32Mx8)*8	
+Dane-Elec	OD1D333-064325I-1MG	MT46V32M8TG(P)-6T rev G	Micron	DR5128-33	6/3/04	2.5	Yes	(32Mx8)*8	

Unbuffered, Non-ECC, DDR400 DIMM Modules 256MB Sizes (32Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+ATP Electronics	AG32L64T8SQC4S	K4H560838D-TCCC rev D	Samsung	SG184T08L1	6/30/03	3	Yes	(32Mx8)*8	EOL
+Centon Electronics	TOP02-D010J	V58C2256804SAT5 rev A	Mosel Vitelic	86SD03	8/7/03	3	Yes	(32Mx8)*8	
+Viking	VI4CU646428DTPL2	K4H560838E-TCCC rev E	Samsung	0000981A	10/8/03	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-512/MC	MT46V32M8TG-5B rev C	Micron	UE0532-AA	9/26/03	3	Yes	(32Mx8)*8	
+Legend	L3264DC7-BU1HDC9C	HY5DU56822CT-D43 rev C	Hyundai	B6U808 rev 1	4/19/04	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-S256/SF	K4H560838F-TCCC rev F	Samsung	UE0832-AA	5/10/04	3	Yes	(32Mx8)*8	
+Dane-Elec	OD1D400-064323I-1MG	MT46V32M8TG(P)-5B rev G	Micron	DR5128-33	5/20/04	3	Yes	(32Mx8)*8	
+Ventura Technology Group	D25AVQ41SV	K4H560838F-TCCC rev F	Samsung	DR5128-33	5/28/04	3	Yes	(32Mx8)*8	
+Ventura Technology Group	D25AVQ41SV	K4H560838F-TCCC rev F	Samsung	DR5128-33	5/28/04	3	Yes	(32Mx8)*8	
+Buffalo	DD4333-S256/MG	MT46V32M8TG(P)-5B rev G	Micron	UE0832-AA	2/9/2005	3	Yes	(32Mx8)*8	
+Legend	L3264DC7-U61HDKSC	HY5DU121622CTP-D43 rev C	Hynix	B6U602 rev 1	11/21/05	3	Yes	(32Mx16)*4	

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Server Board S875WP1-E
Unbuffered, ECC, DDR266 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD266-E512/SD	K4H560838D-TCB0 rev D	Samsung	UE0502-AA	5/1/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CU647228DTHL1	K4H560838D-TCB0 rev D	Samsung	0000839A	6/10/03	2.5	Yes	(32Mx8)*18	
+Dataram	DTM63643B	MT46V32M8TG-75 rev C	Micron	40596A rev A	6/2/03	2.5	Yes	(32Mx8)*18	EOL
Samsung	M381L6423DTL-CA2	K4H560838D-TCA2	Samsung		6/13/03	2	Yes	(32Mx8)*18	
+Legend	L6472DC5-DR1HDC5A	HY5DU56822AT-H rev A	Hyundai	DR720818C rev 1	6/27/03	2.5	Yes	(32Mx8)*18	
Infineon	HYS72D64020GU-7-A	HYB25D256800AT-7A	Infineon		7/15/03	2	Yes	(32Mx8)*18	
+TRS* Tele-Radio-Space GmbH	TRS20157	HYB25D256800BT-7 rev B	Infineon	M0474LA2 rev 2	8/26/03	2	Yes	(32Mx8)*18	
Micron	MT18VDDT6472AG-265C4	MT64v32M8-75 C	Micron		10/10/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CU647228DTHL2	K4H560838E-TCB0 rev E	Samsung	0000927A	10/23/03	2.5	Yes	(32Mx8)*18	
+Viking	VI4CU647228DTHL3	MT46V32M8TG-75 rev C	Micron	0000927A	11/26/03	2.5	Yes	(32Mx8)*18	
+Dataram	DTM63643E	HYB25D256800BT-6 rev B	Infineon	40596A rev A	11/14/03	2.5	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D015O	MT46V32M8TG-75 rev C	Micron	86ESDO4A rev A	12/12/03	2.5	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQB0S	K4H560838E-TCB3 rev E	Samsung	SG184T08L1	12/24/03	2.5	Yes	(32Mx8)*18	

Unbuffered, ECC, DDR333 DIMM Modules
512MB Sizes (64Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT18VDDT6472AG-335C4	MT46V32M8-6TC	Micron		5/15/03	2.5	Yes	(32Mx8)*18	
Infineon	HYS72D64320GU-6-B	HYB25D256800BT-6B	Infineon		6/13/03	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/MC	MT46V32M8TG-6T rev C	Micron	UE0532-AA	7/9/03	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/SD	K4H560838D-TCB3 rev D	Samsung	UE0532-AA	7/15/03	2.5	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQB3S	K4H560838D-TCB3 rev D	Samsung	SG184T08L1 rev 1	9/10/03	2.5	Yes	(32Mx8)*18	EOL
Samsung	M381L6423ETM-CB3	K4H560838E-TCB3	Samsung		9/29/03	2.5	Yes	(32Mx8)*18	
+Ventura Technology Group	D52XVK29SV	K4H560838E-TCB3 rev E	Samsung	V215	11/24/03	2.5	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D021U	MT46V32M8TG-6T rev C	Micron	86ESDO4A rev A	12/09/03	2.5	Yes	(32Mx8)*18	
Infineon	HYS72D64320HU-6-C	HYB25D256800CE-6	Infineon		2/2/04	2.5	Yes	(32Mx8)*18	
Infineon	HYS72D64300HU-6-B	HYB25D512800BE-6C	Infineon		3/4/04	2.5	Yes	(64Mx8)*9	

**Unbuffered, ECC, DDR333 DIMM Modules
512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333-E512/SE	K4H560838E-TCB3 rev E	Samsung	UE0532-AA	6/18/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/SF	K4H560838F-TCB3 rev F	Samsung	UE0532-AA	9/27/04	2.5	Yes	(32Mx8)*18	
+Buffalo	DD333-E512/MG	MT46V32M8-6TG rev G	Micron	UE0532-AA	2/24/05	2.5	Yes	(32Mx8)*18	

**Unbuffered, ECC, DDR400 DIMM Modules
512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Viking	VI4CU647228DTNL1	K4H560838D-TCC4	Samsung	0000927A	5/13/03	3	Yes		EOL
Infineon	HYS72D64320GU-5-B	HYB25D256800B T-5B	Infineon		5/15/03	3	Yes	(32Mx8)*18	
Micron	MT18VDDT6472AG-40BC4	MT46V32M8-5B C	Micron		5/15/03	3	Yes	(32Mx8)*18	
+Dataram	DTM63672A	K4H560838D-TCC4 rev D	Samsung	40570 rev A	5/29/03	3	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQC4S	K4H560838D-TCCC rev D	Samsung	SG184T08L1	6/10/03	3	Yes	(32Mx8)*18	EOL
+Legend	L6472DC7-DR1HDC9B	HY5DU56822BT-D43 rev B	Hyundai	DR720818 C rev 1	6/23/03	3	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D012L	V58C2256804SA T5 rev A	Mosel Vitelic	86ESD04A rev A	7/17/03	3	Yes	(32Mx8)*18	
+Dataram	DTM63672B	HYB25D256800B T-5 rev B	Infineon	40570 rev A	7/21/03	3	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D011K	V58C2256804SA T5 rev A	Mosel Vitelic	86SD03	7/24/03	3	Yes	(32Mx8)*18	
+Smart Modular Technologies	SM6472DDR2N1	HYB25D256800B T-5 rev B	Infineon	L-DIM-184-31-1	7/28/03	3	Yes	(32Mx8)*18	
Samsung	M381L6423ETM-CCC	K4H560838E-TCCC	Samsung		8/20/03	3	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D024X	MT46V32M8TG-5B rev C	Micron	86ESD04 rev A	11/10/03	3	Yes	(32Mx8)*18	
+Centon Electronics	TOP02-D025Y	HYB25D256800B T-5 rev B	Infineon	86ESD04 rev A	11/19/03	3	Yes	(32Mx8)*18	
Micron	MT9VDDT6472AG-40BC1	MT46V64M8-5BC	Micron		1/27/04	3	Yes	(64Mx8)*9	
SimpleTech	ST72C8F64-A05AS	K4H560838E-TCCC rev E	Samsung	1077 rev B	1/26/04	3	Yes	(32Mx8)*18	
+TRS	TRS20173	HYB25D256800B T-5 rev B	Infineon	M0524LA1 rev 1	2/11/04	3	Yes	(32Mx8)*18	
+Legend	L6472DC7-DR1HDC9C	HY5DU56822CT-D43 rev C	Hyundai	DR720818 C1 rev 1	3/5/04	3	Yes	(32Mx8)*18	
+Smart Modular Technologies	SM6472DDR2N1-SF	K4H560838F-TCCC rev F	Samsung	M381L3313 DTM	4/13/04	3	Yes	(32Mx8)*18	
Micron	MT18VDDT6472AG-40BG4	MT46V32M8-5B G	Micron		4/20/04	3	Yes	(32Mx8)*18	
+Viking	VI4CU647228DTPL2	V58C2256804SA T5B rev B	Mosel Vitelic	000981A	4/29/04	3	Yes	(32Mx8)*18	
+ATP Electronics	AG64L72T8SQC4S	K4H560838F-TCCC rev F	Samsung	SG184T08L1 rev 1	5/6/04	3	Yes	(32Mx8)*18	

**Unbuffered, ECC, DDR400 DIMM Modules
512MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
Micron	MT9VDDT6472AG-40BD1	MT46V64M8-5B D	Micron		5/3/04	3	Yes	(64Mx8)*9	
Micron	MT18VDDT6472AG-40BG4	MT46V32M8-5B G	Micron		5/6/04	3	Yes	(32Mx8)*18	
Micron	MT9VDDT6472AG-40BD1	MT46V64MB-5-B	Micron		5/24/2004	3	Yes	(64Mx8)*9	
Infineon	HYS72D64320HU-5-C	HYB25D256800C E-5C	Infineon		6/14/2004	3	Yes	(32Mx8)*18	
+Legend	L6472DC7-MA6HDC9C	HY5DU56822CT-D43 rev C	Hyundai	BDMA83A6 rev 6	6/7/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/IB	HYB25D256800B T-5 rev B	Infineon	UE0532-AA	6/15/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/SF	K4H560838F-TCCC rev F	Samsung	UE0532-AA	6/21/04	3	Yes	(32Mx8)*18	
+Smart Modular Technologies	SM6472DDR2N1-IC	HYB25D256800C E-5 rev C	Infineon	L-DIM-184-31-1	6/17/04	3	Yes	(32Mx8)*18	
+Wintec Industries	3C745684	K4H510838B-TCCC rev B	Samsung	ZK512M68J-A	7/15/04	3	Yes	(64Mx8)*9	
+Legend	L6472DC7-MA6HDC9D	HY5DU56822DT-D43 rev D	Hyundai	BDMA83A6 rev 6	8/27/04	3	Yes	(32Mx8)*18	
+Apacer	77.10738.334	HYB25D256800C E-5 rev C	Infineon	48.16118.0 94 rev 4	9/15/04	3	Yes	(32Mx8)*18	
+Buffalo	DD4333-E512/MG	MT46V32M8TG(P)-5B rev G	Micron	UE0532-AA	10/14/04	3	Yes	(32Mx8)*18	
+TRS	TRS20183	HYB25D256800C E-5 rev C	Infineon	M0524LA1 rev 1	10/12/04	3	Yes	(32Mx8)*18	
Kingston	KVR400X72C3A/512	DD2508AMTA-5B rev M	Elpida	2025193-0F1.A00	1/6/05	3	Yes	(32Mx8)*18	
+Dataram	DTM63672C	HYB25D256800C E-5 rev C	Infineon	40570 rev A	1/28/05	3	Yes	(32Mx8)*18	
+Viking	VI4CU647228DTPL3	MT46V32M8TG-5B rev G	Micron	0000927A rev A	3/28/2005	3	Yes	(32Mx8)*18	

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Server Board S875WP1-E

Unbuffered, Non-ECC, DDR266 DIMM Modules 512MB Sizes (64Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Viking	VI4CU646428DTHL2	K4H560838E-TCB0 rev E	Samsung	0000981A	11/12/03	2.5	Yes	(32Mx8)*16	

Unbuffered, Non-ECC, DDR333 DIMM Modules 512MB Sizes (64Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Buffalo	DD333-512/MC	MT46V32M8TG-6T rev C	Micron	UE0532-AA	8/7/03	2.5	Yes	(32Mx8)*16	
+Viking	VI4CU646428DTKL2	K4H560838E-TCB3 rev E	Samsung	0000981A	10/16/03	2.5	Yes	(32Mx8)*16	
+Ventura Technology Group	D51XVK29SV	K4H560838E-TCB3 rev E	Samsung	V215	12/18/03	2.5	Yes	(32Mx8)*16	
+Dane-Elec	OD1D333-064645I-1NB	NT5DS32M8BT-6K rev B	Nanya	DR1GB8-33	2/20/04	2.5	Yes	(32Mx8)*16	
+Dane-Elec	OD1D333-064645I-1MC	MT46V32M8TG(P)-5B rev C	Micron	DR1GB8-33	3/3/04	2.5	Yes	(32Mx8)*16	
+Dane-Elec	OD1D333-064645I-1MG	MT46V32M8TG(P)-6T rev G	Micron	DR1GB8-33	5/26/04	2.5	Yes	(32Mx8)*16	
+Buffalo	DD333-512/SE	K4H560838E-TCB3 rev E	Samsung	UE0532-AA	8/24/04	2.5	Yes	(32Mx8)*16	
+Buffalo	DD333-1G/MD	MT46V64M8TG(P)-6T rev D	Micron	UE0532-AA	2/1/05	2.5	Yes	(64Mx8)*8	

Unbuffered, Non-ECC, DDR400 DIMM Modules 512MB Sizes (64Mx64)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+ATP Electronics	AG64L64T8SQC4S	K4H560838D-TCCC rev D	Samsung	SG184T08L1	6/26/03	3	Yes	(32Mx8)*16	EOL
+Centon Electronics	TOP02-D011K	V58C2256804SAT5 rev A	Mosel Vitelic	86SD03	7/24/03	3	Yes	(32Mx8)*16	
+Ventura Technology Group	D51AVK29SV	K4H560838E-TCCC rev E	Samsung	V215	8/26/03	3	Yes	(32Mx8)*16	
+ATP Electronics	AG64L64T8SQC4S	K4H560838E-TCCC rev E	Samsung	SG184T08L1	1/20/04	3	Yes	(32Mx8)*16	EOL
+Dane-Elec	OD1D400-064643I-1IB	HYB25D256800BT-5 rev B	Infineon	DR1GB8-33 rev 3	1/28/04	3	Yes	(32Mx8)*16	
+Legend	L6464DC7-BU1HDC9C	HY5DU56822CT-D43 rev C	Hyundai	B6U808 rev 1	3/19/04	3	Yes	(32Mx8)*16	
+Legacy Electronics Inc.	88S5HDL0-1UDG	HYB25D256800BT-5 rev B	Infineon	LE18DDT1848 rev A	5/6/04	3	Yes	(32Mx8)*16	
+Smart Modular Technologies	SM6464DDR2N1-SF	K4H560838F-TCCC rev F	Samsung	M368L6423 ETN	4/23/04	3	Yes	(32Mx8)*16	

**Unbuffered, Non-ECC, DDR400 DIMM Modules
512MB Sizes (64Mx64)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Viking	VI4CU646428DTPL3	K4H560838F-TCCC rev F	Samsung	0000981A	5/13/04	3	Yes	(32Mx8)*16	
+Dane-Elec	OD1D400-064643I- 1MG	MT46V32M8TG(P)- 5B rev G	Micron	DR1GB8-33	5/17/04	3	Yes	(32Mx8)*16	
+Legend	L6464DC7- BU1HDC9D	HY5DU56822DT-D43 rev D	Hyundai	B6U808 rev 1	9/10/04	3	Yes	(32Mx8)*16	
+Smart Modular Technologies	SM6464DDR2N1-IC	HYB25D256800CE-5 rev C	Infineon	184-33-1	10/18/04	3	Yes	(32Mx8)*16	
+Buffalo	DD4333-512/MG	MT46V32M8TG(P)- 5B rev G	Micron	UE0532-AA	1/20/05	3	Yes	(32Mx8)*16	
+Legend	L6464DC7- BU1HDHSC	HY5DU12822CTP- D43 rev C	Hynix	B6U808 rev 1	12/8/05	3	Yes	(64Mx8)*8	

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Server Board S875WP1-E

Unbuffered, ECC, DDR266 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Dataram	DTM63638A	HYB25D256400B C-7 rev B	Infineon	40573A rev A	6/6/03	2	Yes	(64Mx4)*36	
Infineon	HYS72D128020 GU-7-A	HYB25D512800A T-7A	Infineon		6/13/03	2	Yes	(64Mx8)*18	
+Viking	VI4CU287228DX HL1	K4H560438D- TCB0 rev D	Samsung	0000839A	6/16/03	2.5	Yes	(64Mx4)*36	
+Viking	VI4CU287228DX HL2	MT46V64M4TG- 75 rev C	Micron	0000839A	7/29/03	2.5	Yes	(64Mx4)*36	
+TRS* Tele- Radio-Space GmbH	TRS20158	HYB25D512800A T-7 rev A	Infineon	M0474LA2 rev 2	8/14/03	2	Yes	(64Mx4)*36	
+Centon Electronics	TOP02-D016P	MT46V64M8TG- 75 rev C	Micron	86ESDO4A rev A	12/03/03	2.5	Yes	(64Mx8)*18	

Unbuffered, ECC, DDR333 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Smart Modular Technologies	SM12872DDR6H 1	HYB25D512800 AT-6 rev A	Infineon	L-DIM-184- 31-1	11/6/03	2.5	Yes	(64Mx8)*18	
+Centon Electronics	TOP02-D022V	MT46V64M8TG- 6T rev C	Micron	86ESD04A rev A	12/05/03	2.5	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C53 33K4-A	MT46V64M8TG(P)-5B rev C	Micron	50-1402-01- B rev B	3/10/04	2.5	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHB3 S	K4H510838B- TCB3 rev B	Samsung	SG184T08L1 rev 1	4/19/04	2.5	Yes	(64Mx8)*18	
Infineon	HYS72D128320H U-6-B	HYB25D512800 BE-6B	Infineon		4/28/04	2.5	Yes	(64Mx8)*18	
Kingston	KVR333X72C25/ 1G	DD5108ADTA- 6B rev D	Elpida	2025193- 0F1.A00	7/13/04	2.5	Yes	(64Mx8)*18	
+Apacer	76.01220.182	HYB25D512800 BE-5 rev B	Infineon	48.16118.01 4 rev 4	8/19/04	2.5	Yes	(64Mx8)*18	
+Legacy Electronics Inc.	89S6KDL0-1NDG	HYB25D512800 BE-6 rev B	Infineon	LE18DDT184 8 rev A	4/14/05	2.5	Yes	(64Mx8)*18	

Unbuffered, ECC, DDR400 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Smart Modular Technologies	SM12872DDR2 N1	K4H510838B- TCCC rev B	Samsung	M381L3313 DTM	1/16/04	3	Yes	(64Mx8)*18	
+Dataram	DTM63682A	MT46V64M8TG -5B rev C	Micron	40024A rev A	1/22/04	3	Yes	(64Mx8)*18	
Micron	MT18VDDT1287 2AG-40BC1	MT46V64M8- 5BC	Micron		1/27/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333- E1G/MC	MT46V64M8TG -5B rev C	Micron	UE0532-AA	2/13/04	3	Yes	(64Mx8)*18	
Infineon	HYS72D128320 HU-5-B	HYB25D51280 0BE-5B	Infineon		2/23/04	3	Yes	(64Mx8)*18	
+ATP Electronics	AG28L72T8SHC 4M	MT46V64M8TG -5B rev C	Micron	SG184T08L 1	2/27/04	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3 400K4-A	MT46V64M8TG (P)-5B rev C	Micron	50-1402-01- B rev B	3/12/04	3	Yes	(64Mx8)*18	

**Unbuffered, ECC, DDR400 DIMM Modules
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+ATP Electronics	AG28L72T8SHC4S	K4H510838B-TCCC rev B	Samsung	SG184T08L1 rev 1	4/13/04	3	Yes	(64Mx8)*18	
+TRS	TRS20177	K4H510838B-TCCC rev B	Samsung	M0524LA1 rev 1	8/13/04	3	Yes	(64Mx8)*18	
+Ventura Technology Group	D54AYQ40SV	K4H510838B-TCCC rev B	Samsung	DR1GB8-33	5/28/04	3	Yes	(64Mx8)*18	
+Dataram	DTM63682B	MT46V64M8TG(P)-5B rev D	Micron	40024A rev A	5/26/04	3	Yes	(64Mx8)*18	
+TRS	TRS20193	MT46V64M8TG(P)-5B rev C	Micron	M0524LA1 rev 1	5/14/04	3	Yes	(64Mx8)*18	
+Ventura Technology Group	D54AYQ40SV	K4H510838B-TCCC rev B	Samsung	DR1GB8-33	5/28/04	3	Yes	(64Mx8)*18	
+Legend	L1272DC7-MA6HDH9A	HY5DU12822A T-D43 rev A	Hyundai	BDMA83A6 rev 6	6/7/04	3	Yes	(64Mx8)*18	
+Smart Modular Technologies	SM12872DDR2 N1-I	HYB25D51280 0BE-5 rev B	Infineon	L-DIM-184-31-1	6/11/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-E1G/SB	K4H510838B-TCCC rev B	Samsung	UE0532-AA	10/7/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-1G/MD	MT46V64M8TG(P)-5B rev D	Micron	UE0532-AA	12/17/04	3	Yes	(64Mx8)*18	
+Viking	VI4CU287228ET PL1	MT46V64M8TG-5B rev D	Micron	0000927A rev A	3/21/05	3	Yes	(64Mx8)*18	
Samsung	M381L2923BTM-CCC	K4H510838B-TCCC	Samsung		3/15/05	3	Yes	(64Mx8)*18	
Micron	MT18VDDT12872AG-40BD1	MT46V64M8-5B D	Micron		3/22/05	3	Yes	(64Mx8)*18	
+TRS	TRS20217	HYB25D51280 0BE-5 rev B	Infineon	M0524LA1 rev 1	7/25/05	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3400K1-MTD	MT46V64M8TG-5B rev D	Micron	E179889 na	08/10/05	3	Yes	(64Mx8)*18	
+Avant Technology	AVM7228U52C3400K1-SAC	K4H510838C-UCCC rev C	Samsung	E179889 na	10/20/05	3	Yes	(64Mx8)*18	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Server Board S875WP1-E

Unbuffered, Non-ECC, DDR266 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR333 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL

Unbuffered, Non-ECC, DDR400 DIMM Modules 1GB Sizes (128Mx72)

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	EOL
+Legend	L1264DC7-BU1HDH9A	HY5DU12822AT-D43 rev A	Hyundai	B6U808 rev 1	4/9/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-1G/MC	MT46V64M8TG(P)-5B rev C	Micron	UE0532-AA	5/11/04	3	Yes	(64Mx8)*18	
+Buffalo	DD4333-1G/SB	K4H510838B-TCCC rev B	Samsung	UE0532-AA	6/22/04	3	Yes	(64Mx8)*18	
+TRS	TRS20216	HYB25D512800BE-5 rev B	Infineon	M0524LA1 rev 1	7/28/05	3	Yes	(64Mx8)*18	
Buffalo	DD4333-E1GMFJ	MT46V64M8P-5B rev F	Micron	UE0532-AA na	28-Jun-06	3	Yes	(64Mx8)*18	
Smart Modular Technologies	SG12872DDR2N1SC	K4H510838C-UCCC rev C	Samsung	PG52G184N VBZ6RCB rev A	07-Jul-06	3	Yes	(64Mx8)*18	
Smart Modular Technologies	SG12872UDR64835SC	K4H510838C-UCCC rev C	Samsung	M381L3313D TM	11-Jul-06	3	Yes	(64Mx8)*18	

Modules shaded in blue are low profile.

Modules in bold text do not contain Lead.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

Caution: Some modules on this list may contain "stacked" DRAM parts. These parts may have thermal & physical limitations in some chassis configurations. It is advised to verify that your chassis configuration will support "stacked" parts before purchase.

Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	http://www.atpusa.com/	Florence Hsieh Tel 408-732-5831 Fax 408-732-5055 sales@atpusa.com
ATP Electronics -- Taiwan Inc.	http://www.atpusa.com/	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	http://www.avanttechnology.com	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 brads@avanttechnology.com
Aved Memory Products	http://www.avedmemory.com/	
Buffalo Technology	http://www.buffalotech.com/	(800) 967-0959 memory@buffalotech.com
Centon Electronics	http://www.centon.com	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	http://www.corsairmicro.com/	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	http://www.dane-memory.com/	Michal Hassan @ (949)450-2941 or email @ Michal@Dane-memory.com
Dataram	http://www.dataram.com/	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 phenke@dataram.com
GoldenRAM	http://www.goldenram.com	Jason M. Barrette @ 800-222-861 x7546 jasonb@goldenram.com or Michael E. Meyer @800-222-8861 x7512 michaelm@goldenram.com
Hitachi	http://semiconductor.hitachi.com/pointer/	
Hyundai/Hynix Semiconductor	http://www.hea.com/	
Infineon	http://www.infineon.com/business/distribut/index.htm	
ITAUCOM	http://www.itaucum.com.br	
JITCO CO LTD	http://www.jitco.net/	Seong Jeon Tel: 82-32-817-9740 s.jeon@jitco.net
Kingston	http://www.kingston.com	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	http://www.legacyelectronics.com	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	http://www.legend.com.au	
Micron	http://silicon.micron.com/mktg/ http://silicon.micron.com/mktg/mbqual/qual_data.cfm	
MSC Vertriebs GmbH	http://www.msc-ge.com	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 wpe@msc-ge.com
Netlist, Inc	http://www.netlistinc.com	Christopher Lopes 949.435.0025 tel 949.435.0031 fax sales@netlistinc.com

Vendor Name	Web URL	Vendor Direct Sales Info
Peripheral Enhancements	http://www.peripheral.com/	
PNY	http://www.pny.com/internet_explorer/LPB.HTML	
Samsung	http://www.korea.samsungsemi.com/locate/buy/list_na.html	For US customers go to: http://www.mymemorystore.com/
Silicon Tech	http://www.silicontech.com/contact/salescontacts.shtml	
Simple Tech	http://www.simpletech.com	Ron Darwish @ (949) 260-8230 or email @ Rdarwish@Simpletech.com
SMART Modular Technologies	http://www.smartm.com/channel	Gene Patino (949) 439-6167 Gene.Patino@Smartm.com
Swissbit	http://www.swissbit.com	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 tony.cerreta@swissbitna.com
TechnoLinc Corporation	http://www.technolinc.com	David Curtis 510-445-7400 davidc@technolinc.com
TRS* Tele-Radio-Space GmbH	http://www.certified-memory.com http://www.certified-memory.de	Vendor Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 Andreas.gruendl@trs-eu.com
Unigen	http://www.unigen.com	
Ventura Technology Inc	http://www.venturatech.com	Sam Lewis 760 599-0080 ext. 1
Viking InterWorks	http://www.vikinginterworks.com	
Virtium Technology Inc	http://www.virtium.com	Tod Skelton @ (949) 460-0020 ext. 146 or email @ tod.skelton@virtium.com
Legend	http://www.legend.com.au	Tel: 800-338-2361 Fax: 949-459-8577 orderdesk@vikingcomponents.com
Wintec Industries	http://www.wintecindustries.com	Tel 510-360-6300 Fax 510-770-9338

CMTL* (Computer Memory Test Labs)

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

IMPORTANT NOTE

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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